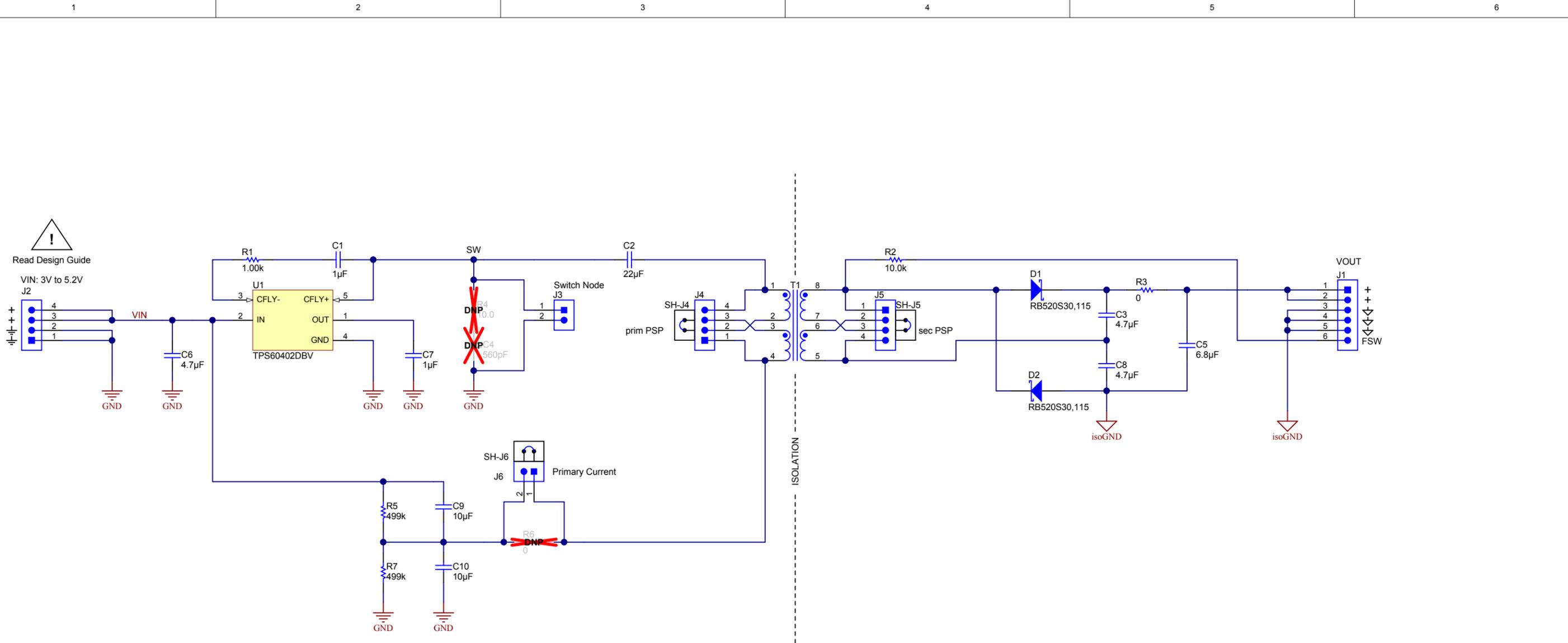


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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/6/2015
TID #: TIDA-00349	Project Title: Isolated DC/DC	
Number: TIDA-00349	Rev: E1	Sheet Title: Block Diagram
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By: AW	File: TIDA-00349_CoverSheet_SchDoc	Size: B
Engineer: JS	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



  
 Read Design Guide  
 VIN: 3V to 5.2V  
 J2

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Orderable: N/A	Designed for: Public Release	Mod. Date: 2/26/2015
TID #: TIDA-00349	Project Title: Isolated DC/DC	
Number: TIDA-00349	Rev: E1	Sheet Title: Isolated DC/DC Converter
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: AW	File: TIDA-00349_IsolatedDCDC.SchDoc	Size: B
Engineer: JS	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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H1 SJ5382 H2 SJ5382 H3 SJ5382 H4 SJ5382

~~DNP~~ FID1 ~~DNP~~ FID2 ~~DNP~~ FID3

PCB LOGO  
CAUTION. READ USER GUIDE BEFORE USE

PCB LOGO Texas Instruments PCB LOGO Pb-Free Symbol

PCB Number: TIDA-00349  
PCB Rev: E1

LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ3  
Label Assembly Note  
This Assembly Note is for PCB labels only

Label Table	
Variant	Label Text
001	TIDA-00349 E1

ZZ5  
Assembly Note  
Jumper/Shunt: SH-J4 on J4-PINs 2-3

ZZ6  
Assembly Note  
Jumper/Shunt: SH-J5 on J5-PINs 2-3

ZZ7  
Assembly Note  
Jumper/Shunt: SH-J6 on J6-PINs 1-2

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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/18/2014
TID #: TIDA-00349	Project Title: Isolated DC/DC	
Number: TIDA-00349	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA-00349_TID_Hardware.SchDoc	Size: B
Engineer: JS	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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